SCBS081H - JANUARY 1991 - REVISED MAY 1997

- State-of-the-Art EPIC-IIB™ BiCMOS Design **Significantly Reduces Power Dissipation**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V • at V_{CC} = 5 V, T_A = 25° C
- High-Impedance State During Power Up and Power Down
- High-Drive Outputs (-32-mA IOH, 64-mA IOI)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Thin Very Small-Outline (DGV) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (J) DIPs

description

These octal bus transceivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT245A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT245B is characterized for operation from -40°C to 85°C.

	FUNCT	UN TABLE					
INP	UTS	OPERATION					
OE	DIR						
L	L	B data to A bus					
L	н	A data to B bus					
н	Х	Isolation					

ELINCTION TABLE



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN54AB	T245A J OR W PACKAGE	
SN74ABT245B.	. DB, DGV, DW, N, OR PW PACKAGE	
	(TOP VIEW)	

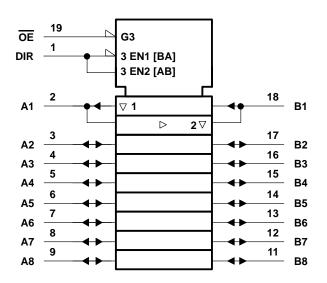
	(,	
DIR [1	U ₂₀	Vcc
A1 [2	19	
A2 [3	18] B1
A3 [4	17] B2
A4 [5	16] B3
A5 [6	15] B4
A6 [7	14] B5
A7 [8	13] B6
A8 [9	12] B7
GND [10	11] B8
			,

SN54ABT245B ... FK PACKAGE (TOP VIEW)

	A2 A1 OE OE	
A3	3 2 1 20 19 4 18 E	31
A4]5 17 [E	32
A3 A4 A5 A6 A7]6 16[E	33
A6]7 15 [E	34
A7	8 10 11 10 12 ¹⁴ E	85
	9 10 11 12 13 	
	A8 GND B8 B7 B7 B6	

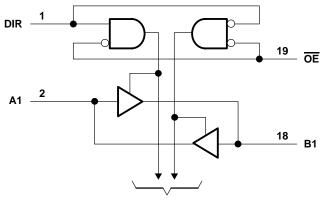
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (except I/O ports) (see N	Note 1)	–0.5 V to 7 V
Voltage applied to any output in the high or pow		
Current into any output in the low state, I _O : SN		
	74ABT245B	
Input clamp current, I_{IK} (V _I < 0)		–18 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DB package	115°C/W
	DGV package	146°C/W
	DW package	
	N package	
	PW package	
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

		SN54ABT245A		SN74ABT245B		UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
VIL	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	V
ЮН	High-level output current		-24		-32	mA
IOL	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
Δt/ΔV _{CC}	Power-up ramp rate			200		μs/V
Т _А	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T	Α = 25°C	;	SN54ABT245A		SN74ABT245B		UNIT	
PA	RAMEIER	TEST CONDITIONS		MIN TYP [†]		MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	lj = -18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5			
Val		V _{CC} = 5 V,	I _{OH} = -3 mA	3			3		3		v	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				v	
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2			
Vei		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			v	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	v	
V _{hys}					100						mV	
	Control inputs	$V_{CC} = 0$ to 5.5 V, V	= V _{CC} or GND			±1		±1		±1		
I A or B ports $V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ VI = V _{CC} or GND		V,			±20		±100		±20	μA		
IOZPU	ŧ	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V},$	OE = X			±50		±50		±50	μΑ	
IOZPD	ŧ	$V_{CC} = 2.1 V \text{ to } 0,$ $V_{O} = 0.5 V \text{ to } 2.7 V,$	OE = X			±50		±50		±50	μA	
I _{OZH} §		$\begin{array}{l} V_{CC} = 2.1 \ V \underline{to} \ 5.5 \\ V_{O} = 2.7 \ V, \ \overline{OE} \geq 2 \end{array}$	V, V			10		10		10	μA	
I _{OZL} §		$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ $V_{O} = 0.5 \text{ V}, \text{ OE} \ge 2 \text{ V}$				-10		-10		-10	μA	
loff		V _{CC} = 0,	$V_{I} \text{ or } V_{O} \leq 4.5 \text{ V}$			±100				±100	μA	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μA	
IO		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-140	-180	-50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high		5	250		250		250	μA	
ICC	A or B ports	$I_{O} = 0,$	Outputs low		22	30		30		30	mA	
		$V_{I} = V_{CC}$ or GND	Outputs disabled		1	250		250		250	μA	
	Data inputs	One	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	mA
∆ICC [#]		Other inputs at V _{CC} or GND	Outputs disabled			50		50		50	μA	
	Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF	
Cio	A or B ports	V _O = 2.5 V or 0.5 V			8						pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 V$.

[‡] This parameter is characterized, but not production tested.

§ The parameters IOZH and IOZL include the input leakage current.

I Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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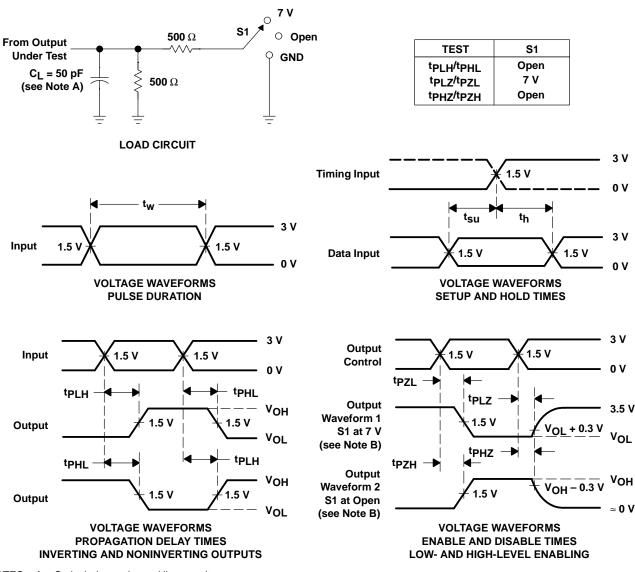
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT245A		SN74ABT245B		UNIT
	(INFOT)	(001-01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	1	2	3.2	0.8	3.8	1	3.6	ns
^t PHL		BUIA	1	2.6	3.5	1	4.2	1	3.9	115
^t PZH	OE	A or B	2	3.5	4.5	1.2	6.2	2	5.6	20
^t PZL	OE	AUB	1.9	4	5.3	1.3	6.8	1.9	6.2	ns
^t PHZ	OE	A or B	2.2	4.4	5.4	2.2	6.1	2.2	5.9	20
^t PLZ	UE	AUIB	1.5	3	4	1.0	4.9	1.5	4.5	ns
^t sk(o) [†]					0.5				0.5	ns

[†] Skew between any two outputs of the same package switching in the same direction. This parameter is warranted but not production tested.



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns. t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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